

03-26-2003

orney Docket No. 16869P-054300US

Form PTO-1595

(Rev. 10-02)

OMB No. 0651-0027 (exp. 6/30/2005)

F



ET

U.S. Department of Commerce
U.S. Patent and Trademark Office

102400346

To the Honorable Commissioner of Patents and Trademarks: _____
_____ original documents or copy thereof

1. Name of conveying party(ies):
Norikazu Nagase
Seichi Higaki
Takao Satoh
3.24.03

Additional name(s) of conveying party(ies) attached? Yes No.

3. Nature of conveyance:
 Assignment Merger
 Security Agreement Change of Name
 Other: _____
Execution Date: January 30, 2003; February 7, 2003 and February 7, 2003

2. Name and address of receiving party(ies)
Name: HITACHI, LTD.
Street Address: 6, Kanda Surugadai, 4-chome, Chiyoda-ku
City: Tokyo Country: Japan

Additional name(s) and address(es) attached? Yes No

4. Application number(s) or patent number(s):
If this document is being filed together with a new application, the execution date of the application is: _____
A. Patent Application No(s): 10/347,118; January 17, 2003
B. Patent No(s): _____
Additional numbers attached? Yes No

6. Total number of applications and patents involved 1
7. Total fee (37 CFR 3.41): \$40.00
 Enclosed
 Authorized to be charged to deposit account

5. Name and address of party to whom correspondence concerning document should be mailed:
Name: Steve Y. Cho
TOWNSEND AND TOWNSEND AND CREW LLP
Two Embarcadero Center, 8th Floor
San Francisco, California 94111-3834
(415) 576-0200

8. Deposit account number: 20-1430
(Attach duplicate copy of this page if paying by deposit account)

DO NOT USE THIS SPACE

9. Statement and signature.
To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.
Steve Y. Cho *[Signature]* 5/19/03
Name of Person Signing Signature Date
Atty. Reg. No. 44,612

Total number of pages including cover sheet, attachments and document 2

Mail documents to be recorded with required cover sheet information to:
Commissioner of Patents and Trademarks, Box Assignments
Washington, D.C. 20231

03/25/2003 PA 3292611 COOPER 00000251 201430 10347118

01 FC:8021 40.00 CH

OFFICE OF PUBLIC RECORDS
2003 MAR 24 AM 8:46
FINANCE SECTION

PATENT
REEL: 013874 FRAME: 0379

ASSIGNMENT
(譲渡証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by HITACHI, LTD., a corporation organized under the laws of Japan, located at 6, Kanda Surugadai 4-chome, Chiyoda-ku, Tokyo, Japan, receipt of which is hereby acknowledged I do hereby sell and assign to said HITACHI, LTD., its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

HIERARCHICAL STORAGE APPARATUS AND CONTROL APPARATUS THEREOF

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said HITACHI, LTD., its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted, as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said HITACHI, LTD.

Signed on the date(s) indicated aside signatures:

INVENTOR(S) (発明者フルネームサイン)	Date Signed (署名日)
1) <u>Yoshi Nagase</u>	<u>1/30/03</u>
2) <u>Seiichi Higashi</u>	<u>2/7/03</u>
3) <u>Takao Satoh</u>	<u>2/7/03</u>
4) _____	_____
5) _____	_____
6) _____	_____
7) _____	_____
8) _____	_____
9) _____	_____
10) _____	_____